

**AMENDMENTS TO THE SPECIFICATION:**

*Please amend Table 3 at page 32, as follows:*

		Comparative Example 1	Comparative Example 2	Comparative Example 3	Comparative Example 4	Comparative Example 5	Comparative Example 6	Comparative Example 7	Comparative Example 8
Construction of Adhesive Film	Base Film	PET	PET	PET	PP	EVA	PET	PET	Thermoplastic PI
	Thickness ( $\mu\text{m}$ )	100	6	250	100	120	50	50	50
	Melting Point ( $^{\circ}\text{C}$ )	255	255	255	160	85	255	255	200 or more
	Main Agent	2	1	1	1	1	3	3	-
	Coating Solution	2	1	1	1	1	3	3	-
	Adhesive Film	12	13	14	15	16	17	18	19
	Thickness of Adhesive Layer ( $\mu\text{m}$ )	10	10	10	10	10	10	120	-
	Adhesive Force [g/25mm]	70	330	8	80	120	40	220	-
	Elastic Modulus [Pa]	$0.5 \times 10^5$	$1.5 \times 10^5$	$1.5 \times 10^5$	$1.5 \times 10^5$	$1.5 \times 10^5$	$\frac{1.2 \times 10^4}{1.5 \times 10^5}$	$1.5 \times 10^5$	$\frac{3.0 \times 10^9}{3.0 \times 10^5}$
	Back Grinding	0	0	0	0	0	0	0	0
Back Processing	Chemical Etching	0	0	0	0	0	0	0	0
	Polishing	0	0	x	0	0	0	0	0
	Plasma Etching	0	0	x	x	x	0	0	0
	Contamination after Back Grinding and Chemical Etching	0	Bad peeling	penetration of etching solution	0	0	6 wafers: adhesive residue	1 wafer: adhesive residue	10 wafers: adhesive residue
	Contamination after Back Grinding and Polishing	0	Bad peeling	penetration of polishing agent	0	0	8 wafers: adhesive residue	Bad peeling	10 wafers: adhesive residue
	Contamination after Back Grinding and Plasma Etching	4 wafers: adhesive residue	Bad peeling	Plasma error	Film deformed	Film deformed	8 wafers: adhesive residue	5 wafers: adhesive residue	10 wafers: adhesive residue
	Wafer Breakage after Back Grinding and Chemical Etching	0	0	-	0	0	0	0	5 wafers broken
	Wafer Breakage after Back Grinding and Polishing	0	0	-	0	0	0	0	8 wafers broken
	Wafer Breakage after Back Grinding and Plasma Etching	0	0	-	2 wafers cracked	6 wafers cracked	0	0	6 wafers broken